

HAT2268C

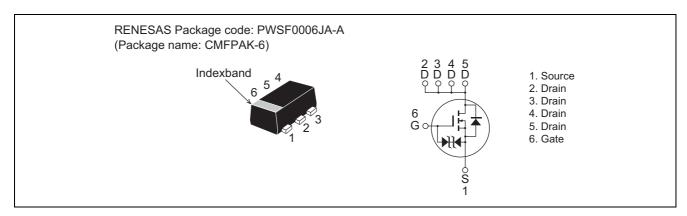
Silicon N Channel MOS FET Power Switching

REJ03G1354-0200 Rev.2.00 Feb 28, 2006

Features

- Low on-resistance $R_{DS(on)} = 27 \ m\Omega \ typ. \ (at \ V_{GS} = 10 \ V)$
- Low drive current.
- High density mounting
- 4.5 V gate drive devices.

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	30	V
Gate to source voltage	V_{GSS}	+20 / -10	V
Drain current	I _D	4	A
Drain peak current	I _D (pulse) ^{Note1}	16	A
Body - Drain diode reverse drain current	I _{DR}	4	A
Channel dissipation	Pch ^{Note 2}	900	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board. (FR4 $40 \times 40 \times 1.6$ mm)

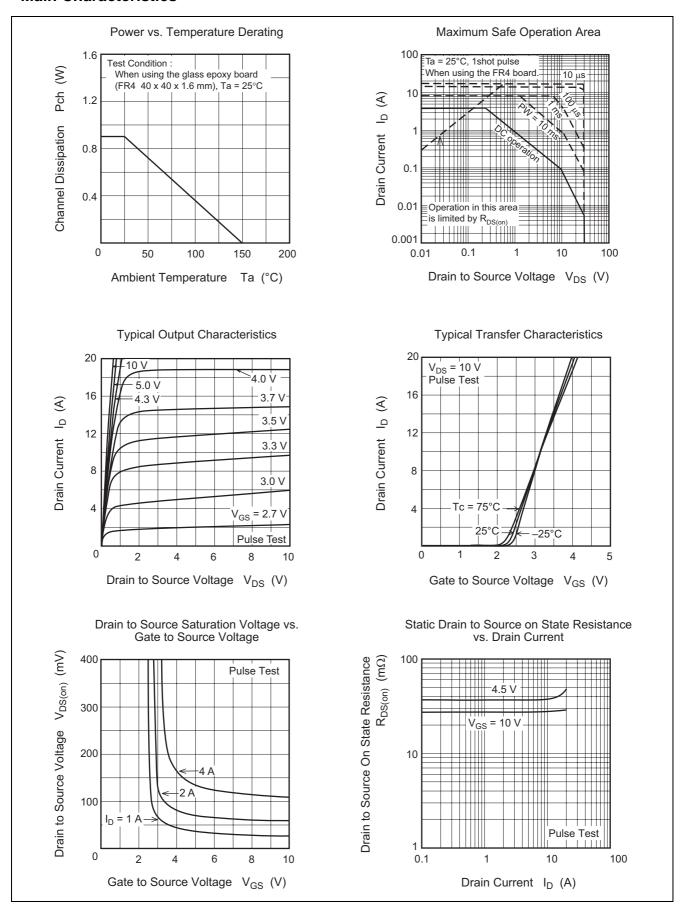
Electrical Characteristics

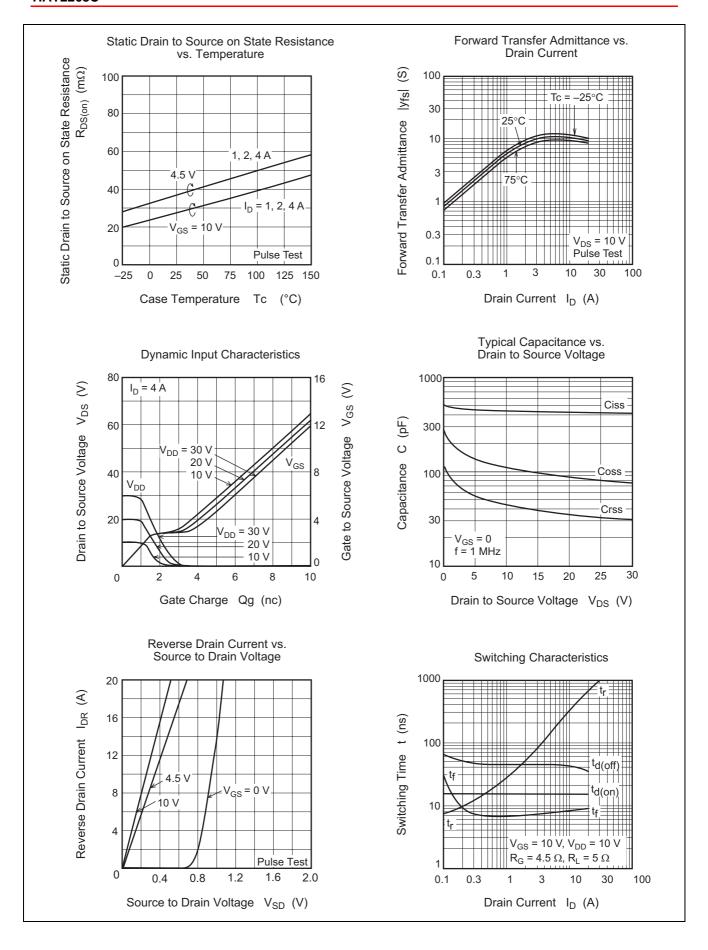
 $(Ta = 25^{\circ}C)$

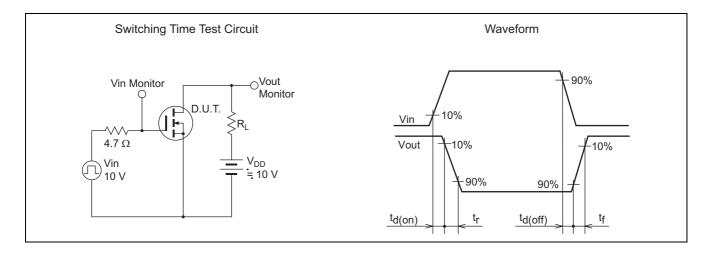
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to Source breakdown voltage	$V_{(BR)DSS}$	30	_	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to Source breakdown voltage	$V_{(BR)GSS}$	+20				$I_G = \pm 10 \ \mu A, \ V_{DS} = 0$
		-10				
Gate to Source leak current	I_{GSS}		_	±10	μΑ	$V_{GS} = +16 / -8 V, V_{DS} = 0$
Drain to Source leak current	I _{DSS}		_	1	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to Source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Drain to Source on state resistance	R _{DS(on)}	_	27	34	mΩ	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note3}}$
	R _{DS(on)}	_	37	54	mΩ	$I_D = 2 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	yfs	5.5	8.5	_	S	$I_D = 2 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	440	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	110	—	pF	f = 1 MHz
Reverse transfer capacitance	Crss		45		pF	
Turn - on delay time	td(on)	_	15	_	ns	$I_D = 2 A, V_{GS} = 10 V,$
Rise time	tr	_	50		ns	$V_{DD} = 10 \text{ V}, R_L = 5 \Omega,$
Turn - off delay time	td(off)	_	45	_	ns	$Rg = 4.7 \Omega$
Fall time	tf	_	7		ns	
Total Gate charge	Qg	_	8	_	nC	V _{DD} = 10 V, V _{GS} = 10 V
Gate to Source charge	Qgs	_	1.5	_	nC	$I_D = 4 A$
Gate to Drain charge	Qgd		1.3		nC	
Body - Drain diode forward voltage	V_{DF}		0.85	1.15	V	$I_F = 4 \text{ A}, V_{GS} = 0^{\text{Note3}}$

Notes: 3. Pulse test

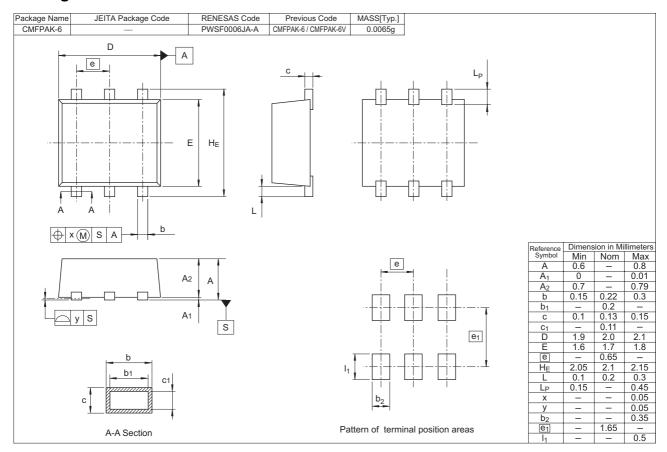
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2268C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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